

Day : Thursday
Date: 12/21/2006

Time: 14:41:07

 **PALM INTRANET**

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1	US 7082031 B2	20060725	Heatsink device and method	361/700	165/104.33; 257/E23.088; 257/E23.099; 361/703; 62/259.2; 62/3.2	Leija; Javier et al.
1	US 7071552 B2	20060704	IC die with directly bonded liquid cooling device	257/712	257/714; 257/E23.098	Ravi; Kramadhati V. et al.
1	US 7063268 B2	20060620	Electro-active fluid cooling system	236/93R	137/67; 236/93A; 251/129.01; 310/365; 361/699; 417/413.1; 62/259.2	Chrysler; Gregory M. et al.
1	US 7034394 B2	20060425	Microelectronic assembly having thermoelectric elements to cool a die and a method of making the same	257/712	257/720; 257/E21.508; 257/E23.079; 257/E23.082; 257/E27.008	Ramanathan; Shriram et al.
1	US 7031155 B2	20060418	Electronic thermal management	361/695	257/722; 257/E23.099; 361/697	Sauciuc; Ioan et al.
1	US 7021891 B2	20060404	Micro-impeller miniature centrifugal compressor	415/98	361/695; 415/203; 416/183; 416/184; 416/185	Sanchez; Eduardo A. et al.
1	US 7012011 B2	20060314	Wafer-level diamond spreader	438/455	438/105	Chrysler; Gregory M. et al.
1	US 6992382 B2	20060131	Integrated micro channels and manifold/plenum using separate silicon or low-	257/717	257/706; 257/708; 257/712; 257/713; 257/714;	Chrysler; Gregory M. et al.

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1	US 6988531 B2	20060124	Micro-chimney and thermosiphon die-level cooling	165/48.1	165/80.2; 165/905; 257/E23.087; 257/E23.088	Chrysler; Gregory M. et al.
1	US 6981380 B2	20060103	Thermoelectric cooling for microelectronic packages and dice	62/3.2	257/E23.082; 62/259.2; 62/3.7	Chrysler; Gregory M. et al.
1	US 6971442 B2	20051206	Method and apparatus for dissipating heat from an electronic device	165/104.25	165/104.21; 165/104.26; 165/104.33; 257/714; 257/715; 257/E23.088; 361/700	Sauciuc; Ioan et al.
1	US 6967840 B2	20051122	Clearing of vapor lock in a microchannel cooling subsystem	361/699	165/80.4; 174/15.1; 257/714; 257/E23.098; 361/700	Chrysler; Gregory M. et al.
1	US 6936497 B2	20050830	Method of forming electronic dies wherein each die has a layer of solid diamond	438/105	148/DIG.12; 257/E21.122; 257/E23.111; 257/E25.013; 257/E29.082; 438/459; 438/519; 438/977	Ravi; Kramadhati V. et al.
1	US 6921706 B2	20050726	Electronic assembly including a die having an integrated circuit and a layer of diamond to transfer heat	438/460	257/E21.122; 257/E21.568; 257/E23.111; 438/113	Chrysler; Gregory M. et al.
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1	US 6868898 B2	20050322	Heat pipe having an inner retaining wall for wicking components	165/104.26	165/185; 174/15.2; 361/700	Chau; David S. et al.
1	US 6862183 B2	20050301	Composite fins for heat sinks	361/704	165/185; 165/80.3; 174/16.3; 257/722; 257/E23.103; 29/890.03; 361/709; 361/719	Chrysler; Gregory M. et al.
1	US 6845622 B2	20050125	Phase-change refrigeration apparatus with thermoelectric cooling element and methods	62/3.7	165/104.21; 62/3.2	Sauciuc; Ioan et al.
1	US 6795311 B2	20040921	Method and apparatus for cooling portable computers	361/687	361/704; 710/303; 710/304	Pokharna; Himanshu et al.
1	US 6785134 B2	20040831	Embedded liquid pump and microchannel cooling system	361/699	165/80.4; 257/714; 257/715; 257/E23.087; 257/E23.098; 361/689; 361/698; 361/700	Maveety; James G. et al.
1	US 6770966 B2	20040803	Electronic assembly including a die having an integrated circuit and a layer of diamond to	257/706	257/E21.122; 257/E21.568; 257/E23.111	Chrysler; Gregory M. et al.

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1	US 6706562 B2	20040316	Electronic assembly with high capacity thermal spreader and methods of manufacture	438/125	257/E23.101; 257/E23.111; 438/122	Mahajan; Ravi V. et al.
1	US 6661660 B2	20031209	Integrated vapor chamber heat sink and spreader and an embedded direct heat pipe attachment	361/700	165/104.26; 165/80.3; 165/80.4; 174/15.2; 174/16.3; 257/714; 257/718; 257/E23.088; 361/702; 361/703; 361/704; 361/717; 361/718; 361/719	Prasher; Ravi et al.
1	US 6653730 B2	20031125	Electronic assembly with high capacity thermal interface	257/704	257/712; 257/713; 257/E23.101; 257/E23.111	Chrysler; Gregory M. et al.
1	US 6650542 B1	20031118	Piezoelectric actuated jet impingement cooling	361/699	165/104.33; 165/80.4; 174/15.1; 257/714; 257/E23.1; 361/698; 361/704	Chrysler; Gregory M. et al.
1	US 6646874 B2	20031111	Mobile computer system with detachable thermoelectric module for enhanced cooling capability in a docking station	361/687	62/3.2	Pokharna; Himanshu et al.
1	US 6639799 B2	20031028	Integrated vapor chamber heat sink and spreader and an embedded direct heat pipe attachment	361/700	165/80.4; 174/15.2; 257/714; 257/715; 257/E23.088; 361/203;	Prasher; Ravi et al.

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1	US 6636423 B2	20031021	Composite fins for heat sinks	361/703	165/185; 257/722; 257/E23.103; 29/890.03	Rinella; Agostino C. et al.
1	US 6609561 B2	20030826	Tunnel-phase change heat exchanger	165/104.33	165/104.21; 165/80.4; 174/15.2; 257/715; 257/E23.088; 361/700	Sauciuc; Ioan et al.
1	US 6561267 B2	20030513	Heat sink and electronic circuit module including the same	165/185	165/80.3; 174/16.3; 257/722; 257/E23.103; 257/E23.105; 361/695; 361/704	Sauciuc; Ioan et al.
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1	US 6213194 B1	20010410	Hybrid cooling system for electronics module	165/80.3	165/80.4; 257/714; 257/722; 361/696; 361/697;	Chrysler; Gregory M. et al.

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1	US 6205796 B1	20010327	Sub-dew point cooling of electronic systems	62/94	361/700; 62/259.2	Chu; Richard C. et al.
1	US 6035655 A	20000314	Modular refrigeration system	62/259.2	62/196.4	Hare; Jeffrey J. et al.
1	US 6034872 A	20000307	Cooling computer systems	361/699	165/165; 165/170; 361/735; 62/259.2	Chrysler; Gregory M. et al.
1	US 6023410 A	20000208	Extended cooling for portable computers	361/681	361/687; 361/690; 361/707	Chu; Richard C. et al.
1	US 5970731 A	19991026	Modular refrigeration system	62/196.4	62/228.4	Hare; Jeffrey J. et al.
1	US 5963425 A	19991005	Combined air and refrigeration cooling for computer systems	361/695	165/104.33; 165/80.4; 174/15.1; 361/699; 454/186; 62/259.2	Chrysler; Gregory M. et al.
1	US 5954127 A	19990921	Cold plate for dual refrigeration system	165/170	165/164; 165/165; 361/700; 62/259.2	Chrysler; Gregory M. et al.
1	US 5953930 A	19990921	Evaporator for use in an extended air cooling system for electronic components	62/259.2	165/104.21; 165/104.33; 257/E23.088; 361/700	Chu; Richard C. et al.
1	US 5934364 A	19990810	Cold plate for dual refrigeration systems	165/170	165/164; 165/80.2	Chrysler; Gregory M.. et al.
1	US 5926368 A	19990720	Enhanced air cooling system with attached cooling unit	361/695		Chrysler; Gregory Martin et al.
1	US 5896922 A	19990427	Cold plate for dual refrigeration systems	165/165	165/146; 165/170; 62/259.2	Chrysler; Gregory M. et al.
1	US 5825620	19981020	Enhanced air cooling system	361/695		Chrysler; Gregory

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1	US 5761037 A	19980602	Orientation independent evaporator	361/700	165/104.26; 165/80.4; 257/E23.088; 62/259.2	Anderson; Timothy Merrill et al.
1	US 5758418 A	19980602	Method of making an ultra high-density, high-performance heat sink	29/890.03	257/E23.105; 29/890.054	Chrysler; Gregory Martin et al.
1	US 5743794 A	19980428	Method for field upgrading of air cooling capacity	454/184	361/695	Chrysler; Gregory Martin et al.
1	US 5719745 A	19980217	Extended surface cooling for chip stack applications	361/704	174/16.3; 257/722; 257/E25.013; 361/710	Agonafer; Dereje et al.
1	US 5704419 A	19980106	Air flow distribution in integrated circuit spot coolers	165/121	165/80.3; 257/E23.099; 361/697	Agonafer; Dereje et al.
1	US 5615084 A	19970325	Enhanced flow distributor for integrated circuit spot coolers	361/697	165/121; 165/80.3; 257/E23.099; 361/719; 415/178; 415/213.1	Anderson; Timothy M. et al.
1	US 5609202 A	19970311	Enhanced flow distributor for integrated circuit spot coolers	165/80.3	165/122; 165/124; 165/126; 165/185; 165/96; 174/16.3; 257/722; 257/E23.099; 361/697	Anderson; Timothy M. et al.
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1	US 5482113 A	19960109	Convertible heat exchanger for air or water cooling of electronic circuit components and the like	165/137	165/122; 165/157	Agonafer; Dereje et al.
1	US 5456081 A	19951010	Thermoelectric cooling assembly with optimized fin structure for improved thermal performance and manufacturability	62/3.7	136/204; 165/185; 165/80.2; 257/E23.082; 62/259.2	Chrysler; Gregory M. et al.
1	US 5412536 A	19950502	Local condensation control for liquid impingement two-phase cooling	361/700	165/104.26; 165/80.5; 174/15.2; 257/715; 257/E23.088	Anderson; Timothy M. et al.
1	US 5370178 A	19941206	Convertible cooling module for air or water cooling of electronic circuit components	165/137	165/185; 165/80.3; 165/80.4; 257/E23.098; 257/E23.099; 361/697; 361/699; 361/703	Agonafer; Dereje et al.
1	US 5303555 A	19940419	Electronics package with improved thermal management by thermoacoustic heat pumping	62/6	257/E23.094; 257/E23.099; 60/520; 62/259.2	Chrysler; Gregory M. et al.
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